

Title (en)

MULTI-LAYER COMPONENT HAVING EXTERNAL CONTACTING AND METHOD FOR PRODUCING A MULTI-LAYER COMPONENT HAVING EXTERNAL CONTACTING

Title (de)

VIELSCHICHTBAUELEMENT MIT EINER AUSSENKONTAKTIERUNG UND VERFAHREN ZUR HERSTELLUNG EINES VIELSCHICHTBAUELEMENTS MIT EINER AUSSENKONTAKTIERUNG

Title (fr)

ÉLÉMENT STRUCTURAL MULTICOUCHE POURVU D'UN ÉLÉMENT DE MISE EN CONTACT ÉLECTRIQUE EXTÉRIEUR ET PROCÉDÉ DE FABRICATION D'UN ÉLÉMENT STRUCTURAL MULTICOUCHE POURVU D'UN ÉLÉMENT DE MISE EN CONTACT ÉLECTRIQUE EXTÉRIEUR

Publication

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Application

**EP 13720418 A 20130506**

Priority

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- EP 2013059384 W 20130506

Abstract (en)

[origin: WO2014000930A2] The invention relates to a multi-layer component having a base body (1) which has a stack made of dielectric layers and internal electrode layers (3a, 3b), and having external contacting (4a, 4b) for electrical contacting of the electrode layers (3a, 3b), wherein the external contacting (4a, 4b) has a first layer (6) and a second layer (7) and wherein the first layer (6) and the second layer (7) are burned-in.

IPC 8 full level

**H01G 4/232** (2006.01); **H01G 4/30** (2006.01); **H01L 41/047** (2006.01); **H01L 41/293** (2013.01)

CPC (source: EP US)

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Citation (search report)

See references of WO 2014000930A2

Citation (examination)

JP 2002050803 A 20020215 - TOKIN CERAMICS CORP

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Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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